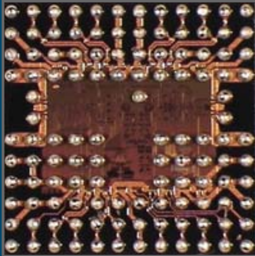
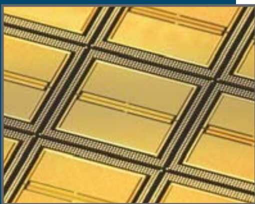
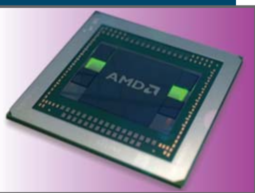
Advanced Packaging Update:

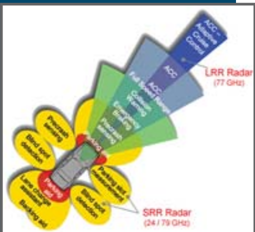
Market and Technology Trends

Vol. 1-1015









This issue of the Advanced Packaging Update features special coverage of the latest developments in fan-out wafer level packages (FO-WLPs), including applications and suppliers. A market forecast is provided, including a break out for high-density FO-WLP. The latest developments in silicon interposers are presented and a new market forecast is included. A major section of the report is focused on autonomous driving and the latest automotive safety features, including packaging trends. An economic analysis examines macroeconomic trends and their impact on the semiconductor packaging and assembly industry.

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